



Photo courtesy AMD Saxony

AMD Advanced Micro Devices FAB 30 200mm Semiconductor Facility Dresden, Germany



Case Study



View of the office building & fab

Concept

New construction of a 200mm wafer fab for AMD Advanced Micro Devices in Dresden, Germany. This was AMD's first international project outside of the USA.

A three-level fab consisting of:

- · Lower level for equipment and sub-main services.
- · Mid-section level for process support services.
- · Cleanroom level with circulating air return area and plenum in the roof truss area including filter fan units.

Location & Features The newly built development is located on company grounds in the north of Dresden just 3 km from Dresden Airport. The total developed project as built and in operation as of Sept. 1998 was 231.000m². The total greenfield site consists of approximately 450.000m² allowing for future development on the same premises.

> The major building elements include: The FAB, spine, central utilities building (CUB), remote and office building. In addition, a 23 MW co-generation plant was constructed on an adjacent site to supply the facility with power, heating and cooling services.

INTEC Services

We were consultant and client representative for both the facilities & finance infrastructure departments.

Our scope of works for the finance department included budget & cost control, claim- & change order management, bank reporting & cashflow forecasting, weekly & monthly cost /- construction reports to the client. During Hook Up phases 1 to 3 we performed quantity surveying services checking remeasurements and auditing invoices.

Our scope of services for the facilities department included oversight and co-ordination of AMD's construction management & the design/build contractor. Tender negotiations, quality control, guarantee & warranty issues were also successfully managed by our team.

compiled extensive an Comparison Benchmarking Document of both AMD's Fab 30 (Dresden) and Fab 25 (Austin, Texas) facilities including a Lessons Learned Analysis of design and construction during the base build phase. This very important and confidential document identified issues, defined roles, objectives & responsibilities while highlighting and recommending necessary improvements for AMD to follow in order to make future projects successful.

Project Data

231.000 m² Total developed site area:

Other building and support areas:

64.300 m² Fab & support Office 21.000 m² Cleanroom (SMIF) 14.000 m² Category Technology generation 100 Turbulent 0.13µ (Logic)

Milestones

Groundbreaking: Oct., 1996 April 1997 Beginning of Construction: Tool Move-In: May, 1998 First Silicon: Dec 1998

Total Investment

US \$ 2,4 Billion (building and equipment as of 2003) Design & build contract with open book procedure.

Client

AMD Advanced Micro Devices Dresden, Germany www amd com www.amd-saxony.de

Project- & Commercial Management

I N T E C International Construction Consultants GmbH & Co. KG

Project Management

Hanscomb International Construction Consultants Berlin

Design & Build Contractor

M+W Zander Facility Engineering GmbH Stuttgart

Architects & Engineers

Alfonso Mercurio (AMA Group)

Achammer Tritthart & Partner (ATP) Innsbruck, Austria

M+W Zander Facility Engineering GmbH Stuttgart



View inside the Cleanroom Photos courtesy of AMD Saxony

INTEC

International Construction Consultants GmbH & Co. KG

Zur Wetterwarte 27 01109 Dresden, Germany

P.O. Box / Postfach 23 02 19 01112 Dresden, Germany

Tel.: +49 (0) 351 / 656 333 - 92 Fax: +49 (0) 351 / 656 333 - 98 Email: info@intec-consult.com Internet: www.intec-consult.com